

2SK3076(L),2SK3076(S)

Silicon N Channel MOS FET
High Speed Power Switching

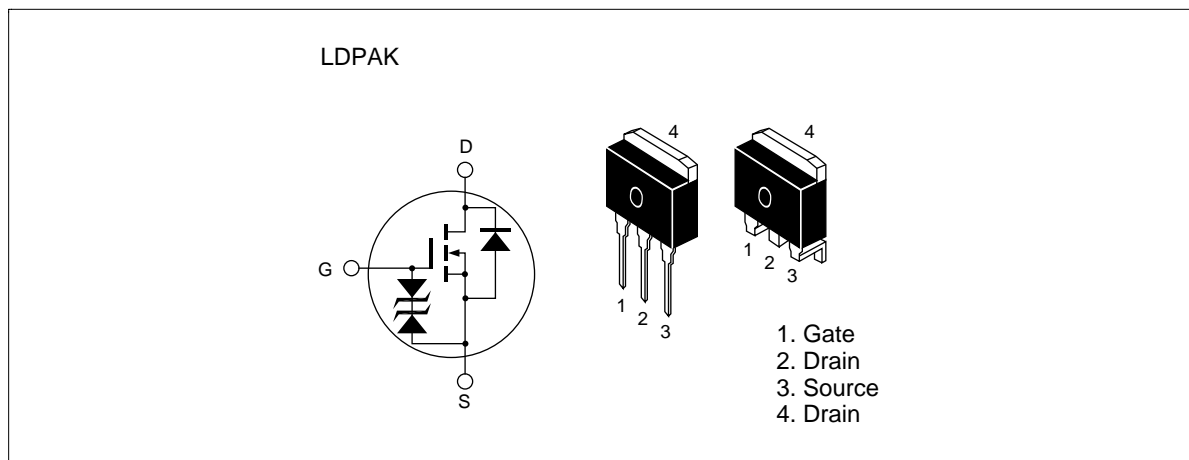
HITACHI

ADE-208-656 (Z)
1st. Edition
Jun 1998

Features

- Low on-resistance
- High speed switching
- Low drive current.
- Built-in fast recovery diode ($t_{rr}=120$ ns)

Outline



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Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	500	V
Gate to source voltage	V_{GSS}	±30	V
Drain current	I_D	7	A
Drain peak current	$I_{D(pulse)}$ ^{Note1}	28	A
Body-drain diode reverse drain current	I_{DR}	7	A
Channel dissipation	P_{ch} ^{Note2}	60	W
Channel temperature	T_{ch}	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

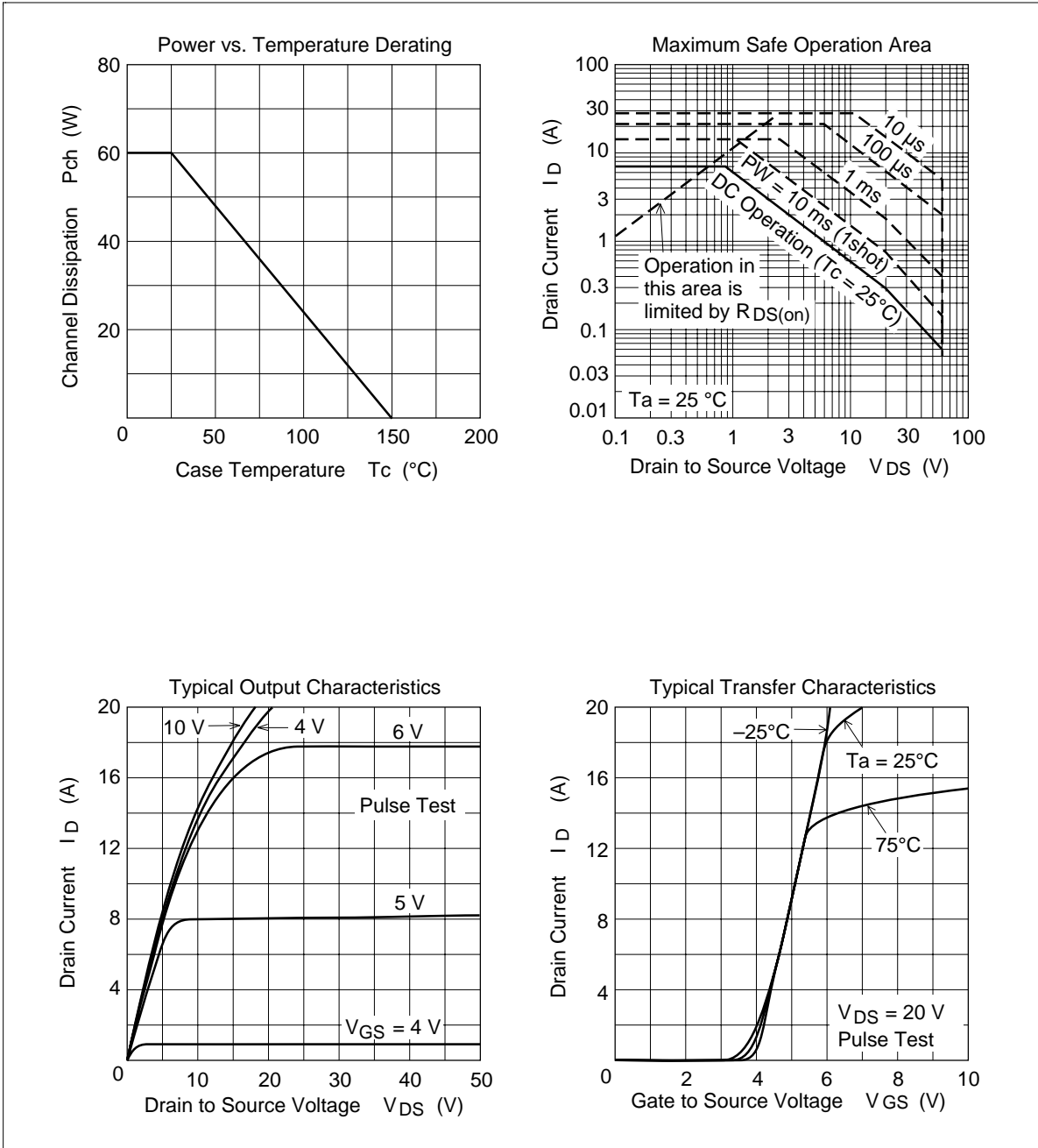
Note: 1. $PW \leq 10\mu s$, duty cycle $\leq 1\%$
 2. Value at $T_c = 25^\circ C$

Electrical Characteristics (Ta = 25°C)

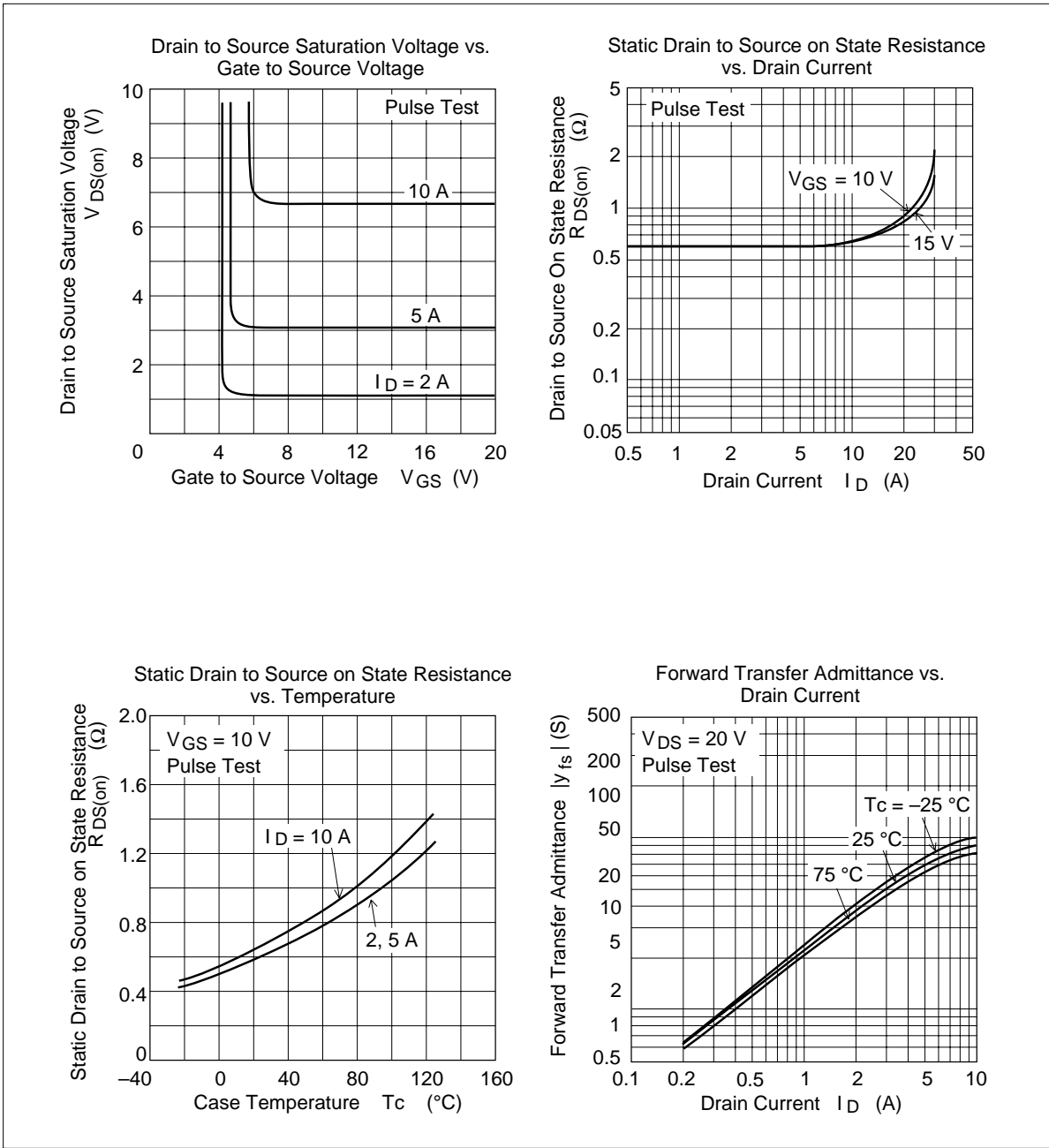
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	500	—	—	V	$I_D = 10mA, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	—	—	V	$I_G = \pm 100\mu A, V_{DS} = 0$
Gate to source leak current	I_{GSS}	—	—	±10	μA	$V_{GS} = \pm 25V, V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	250	μA	$V_{DS} = 400V, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	—	3.0	V	$I_D = 1mA, V_{DS} = 10V$
Static drain to source on state resistance	$R_{DS(on)}$	—	0.7	0.9	Ω	$I_D = 4A, V_{GS} = 10V$ ^{Note4}
Forward transfer admittance	$ y_{fs} $	3.5	6.0	—	S	$I_D = 4A, V_{DS} = 10V$ ^{Note4}
Input capacitance	C_{iss}	—	1100	—	pF	$V_{DS} = 10V$
Output capacitance	C_{oss}	—	310	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	C_{rss}	—	50	—	pF	$f = 1MHz$
Turn-on delay time	$t_{d(on)}$	—	15	—	ns	$I_D = 4A, V_{GS} = 10V$
Rise time	t_r	—	55	—	ns	$R_L = 7.5\Omega$
Turn-off delay time	$t_{d(off)}$	—	100	—	ns	
Fall time	t_f	—	48	—	ns	
Body-drain diode forward voltage	V_{DF}	—	0.9	—	V	$I_F = 7A, V_{GS} = 0$
Body-drain diode reverse recovery time	t_{rr}	—	120	—	ns	$I_F = 7A, V_{GS} = 0$ $diF/dt = 100A/\mu s$

Note: 4. Pulse test

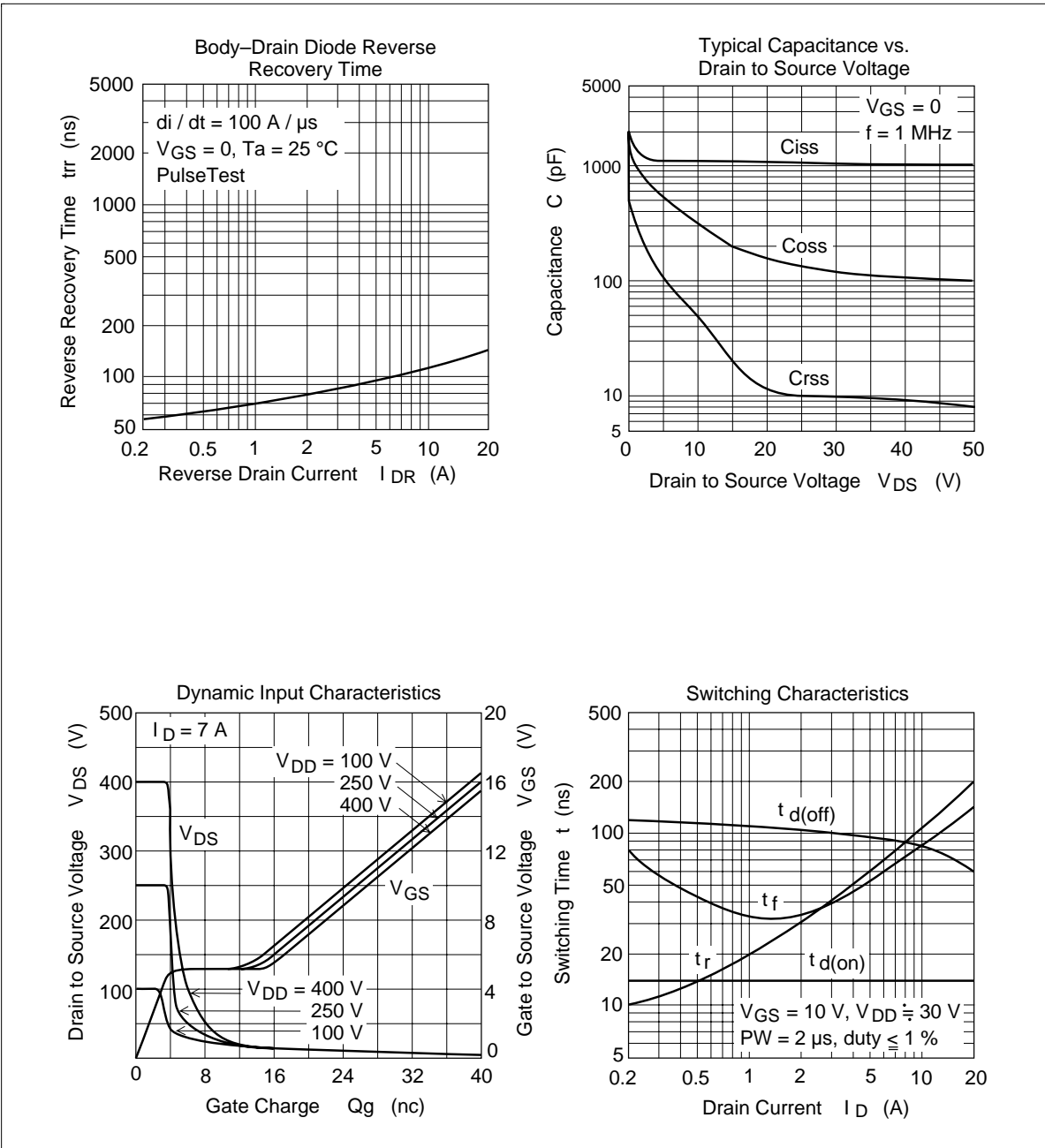
Main Characteristics



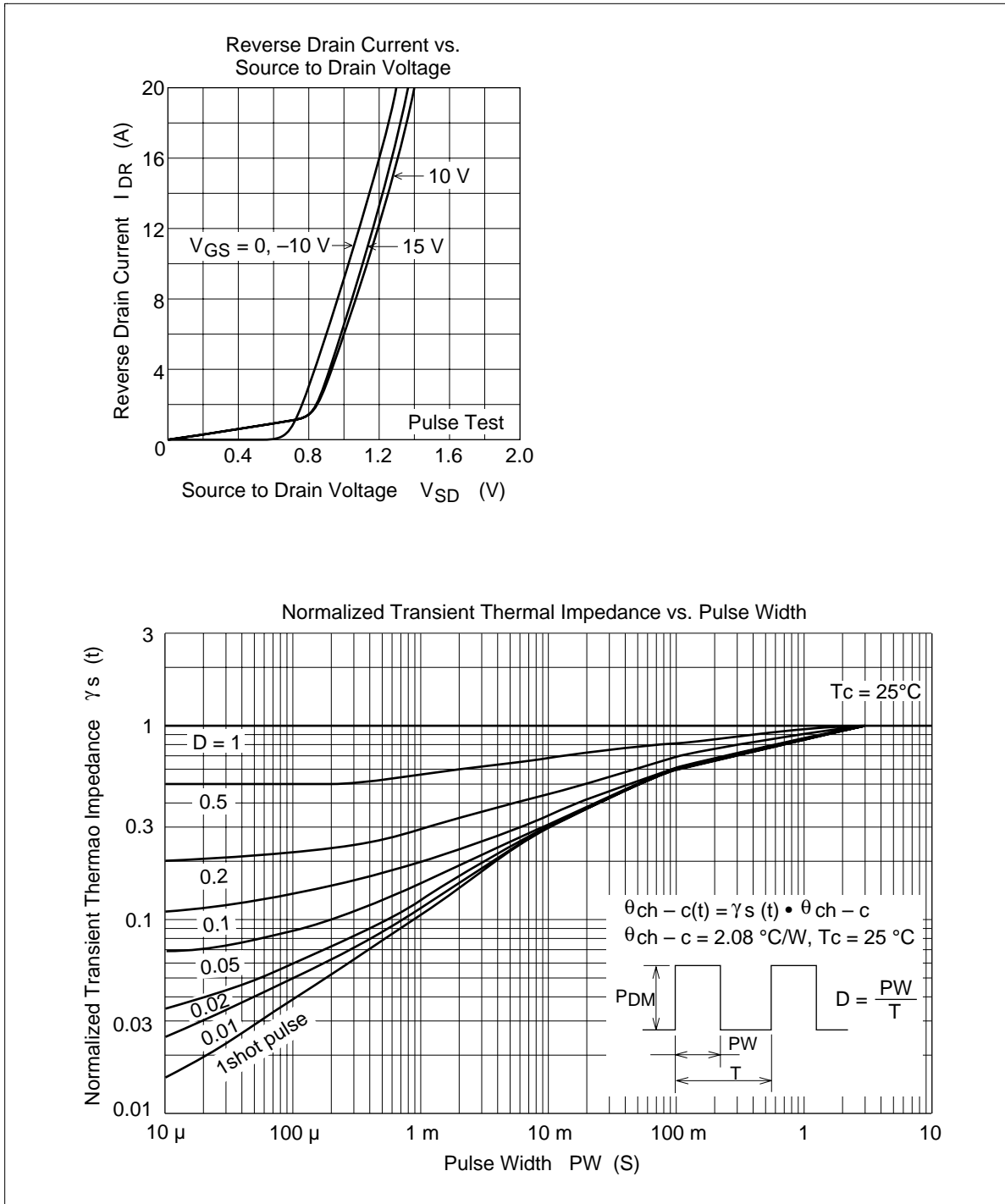
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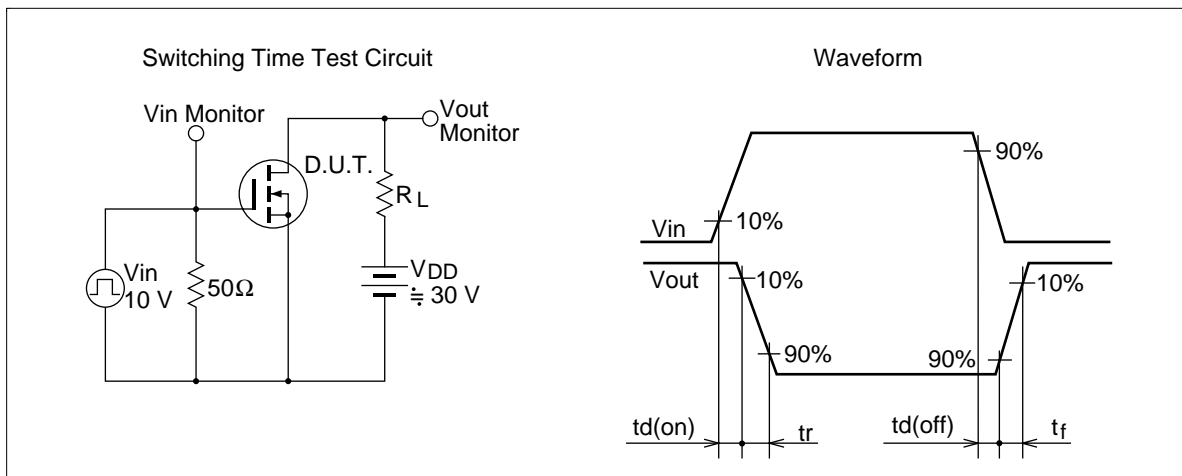
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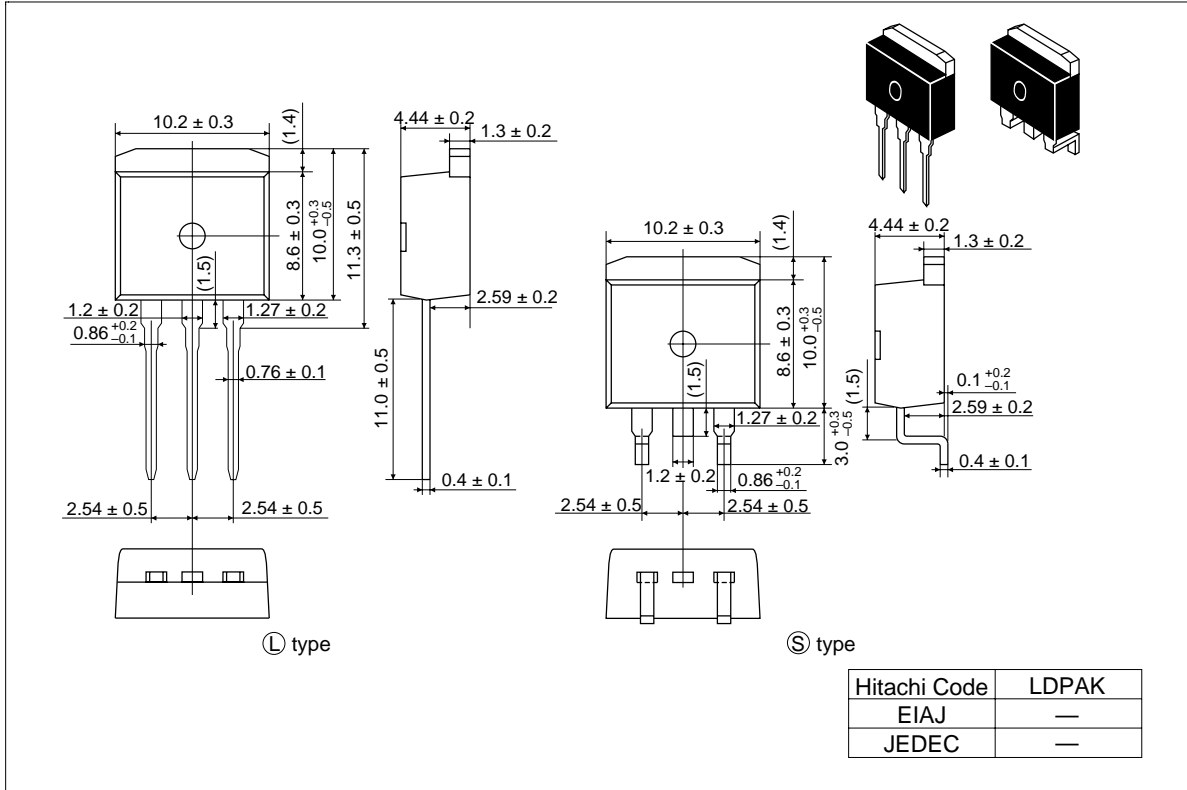
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Package Dimensions

Unit: mm



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Hitachi, Ltd.

Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1> (408) 433-0223

Hitachi Europe GmbH
Electronic components Group
Dornacher StraÙe 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building, No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX

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